

## PATENT ASSIGNMENT COVER SHEET

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Assignment ID: PAT1635819

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	NUNC PRO TUNC ASSIGNMENT
<b>EFFECTIVE DATE:</b>	05/14/2021
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Michael J. Lembo	11/14/2024
<b>RECEIVING PARTY DATA</b>	
<b>Company Name:</b>	CertainTeed Ceilings Corporation
<b>Street Address:</b>	20 Moores Road
<b>City:</b>	Malvern
<b>State/Country:</b>	PENNSYLVANIA
<b>Postal Code:</b>	19355
<b>PROPERTY NUMBERS Total: 3</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17320651
<b>PCT Number:</b>	US2132430
<b>Application Number:</b>	63025050
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<b>ATTORNEY DOCKET NUMBER:</b>	20-167
<b>NAME OF SUBMITTER:</b>	Amy Peterson
<b>SIGNATURE:</b>	Amy Peterson
<b>DATE SIGNED:</b>	11/15/2024
<b>Total Attachments: 2</b>	
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source=20-167_Utility combo declaration and assignment#page2.tiff	

19-CE-0405

**DECLARATION AND ASSIGNMENT**

U.S. Provisional Patent Application 63/025050, filed May 14, 2020  
International Patent Application PCT/US2021/032430, filed May 14, 2021  
United States Patent Application 17/320,651, filed May 14, 2021  
Canadian Patent Application 3178053, filed May 14, 2021

**Section 1: Declaration**

As a below named inventor, I direct this Declaration to U.S. Patent Application no. 17/320,651, filed May 14, 2021. I hereby declare that:

U.S. Patent Application no. 17/320,651 was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**Section 2: Assignment**

In consideration of One Dollar (\$1.00) and other good and valuable considerations in hand paid, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby confirm the prior assignment, and assign, effective May 14, 2021, to:

**CertainTeed Ceilings Corporation  
20 Moores Road  
Malvern, PA 19355  
United States of America**

its successors and assigns, their entire right, title and interest in the invention or improvements of the undersigned disclosed the patent application(s) identified above and relating to:

**Adjustable Ceiling Panel, Method of Manufacture, and Ceiling Panel System**

and in said application(s) and any and all other applications, both United States and foreign, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States and foreign countries, which may be obtained on any of said applications, and in any reissue or extension of such patents, and further assigns to said assignee the priority right provided by the International Convention. The undersigned hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned were employees of the assignee at the time of making their contribution to the invention or improvements, and as such confirm that all rights in the invention transferred ab initio to the assignee. Each of the undersigned warrants themselves to be the owner of (other than any right, title or interest already held by the assignee) the entire right, title and interest in said invention or improvements and to have the right to make this assignment, and further warrant (other than any right, title or interest already held by the assignee) that there are no outstanding prior assignments, licenses, or other encumbrances on the interest herein assigned (other than any right, title or interest already held by the assignee).

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For said considerations the undersigned hereby agree, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation and substitute applications for said invention or improvements, and any necessary oath, affidavit or declaration relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application and any and all applications and other documents for Letters Patent in foreign countries on said invention or improvements, that said assignee, its successors or assigns may deem necessary or expedient, and for the said considerations the undersigned authorize said assignee to apply for patents for said invention or improvements in its own name in such countries where such procedure is proper and further agree, upon the request of said assignee, its successors and assigns, to cooperate to the best of the ability of the undersigned with said assignee, its successors and assigns, in any proceedings or transactions involving such applications or patents, including the preparation and execution of preliminary statements, giving and producing evidence, and performing any and all other acts necessary to obtain, maintain and enforce said Letters Patent, both United States and foreign, and vest all rights therein hereby conveyed in the assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by the said assignee, its successors and assigns, to the full end of the term for which said Letters Patent will be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment had not been made.

My signature here applies to both the Declaration section and the Assignment section above.

Dated: 11/14/2024

Signed by:  
*Michael J. Lembo*  
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By: \_\_\_\_\_  
Michael J. Lembo